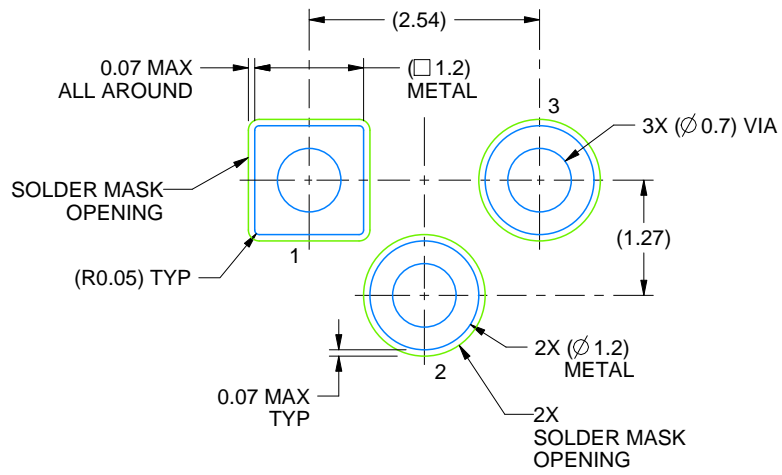


4219876/A 01/2017

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-46.



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE:12X

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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